

Title (en)

A POLISHING PAD FOR CHEMICAL MECHANICAL POLISHING

Title (de)

POLIERKISSEN FÜR CHEMISCH-MECHANISCHES POLIEREN

Title (fr)

TAMPON A POLIR POUR POLISSAGE MECANO-CHIMIQUE

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Application

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Abstract (en)

[origin: US2005055885A1] The present invention provides in one embodiment, a polishing pad 100 for chemical mechanical polishing. The polishing pad comprises a polishing body 110. The polishing body comprises a thermoplastic foam substrate 115 having a surface 120 comprising concave cells 125. A polishing agent 130 coats an interior surface 135 of the concave cells. The polishing agent comprises an inorganic metal oxide that includes carbides or nitrides. Yet another embodiment of the present invention is a method for preparing a polishing pad 200.

IPC 8 full level

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